

**PACKAGED SEMICONDUCTOR DEVICE AND METHOD OF
FORMATION**

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Abstract of the Disclosure

A packaged semiconductor device (20) has a first integrated circuit die (28) having a top surface with active electrical circuitry implemented thereon. The first die (28) is mounted in a cavity (21) of a first heat spreader (22). A second die (36) having electrical circuitry implemented on a top surface is attached to the top surface of the first die (28). Both of the die (28 and 36) are electrically connected to a substrate (24) mounted on the first heat spreader (22). A second heat spreader (40) is mounted on the top surface of the second die (36). The second heat spreader (40) provides an additional path for thermal dissipation of heat generated by the second die (36).